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International Application No.	0	For receiving Office use only	
Name of receiving Office and PCT	0-1	International Application No.	
International Application*   PCT-EASY Version 2.92   (updated 01.07.2003)	0-2	International Filing Date	
0-4-1 Prepared using PCT-EASY Version 2.92 (updated 01.07.2003)  0-5 Petition The undersigned requests that the present international application be processed according to the Patent Cooperation Treaty  0-6 Receiving Office (specified by the applicant) 0-7 Applicant's or agent's file reference  1 Title of invention METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER, METHOD FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER, AND SYSTEM FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER, AND SYSTEM FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER  11 Applicant 11-1 This person is: 11-2 Applicant for all designated States except US 11-4 Name Shin-Etsu Handotai Co., Ltd. 14-2, Marunouchi 1-chome Chiyoda-ku, Tokyo 100-0005 1 Japan 11-6 State of nationality 11-7 State of residence 11-9 Facsimile No. 10-3-3214-1931 11-9 Facsimile No. 10-3-3214-1931 11-1 This person is: applicant and inventor 11-2 Applicant for US only 11-4 Applicant and Control of the Address: applicant and inventor 11-5 Address: applicant and inventor 11-6 State of nationality 11-6 State of nationality 11-6 State of nationality 11-7 Tatsuo 11-7 Chame Chiyoda-ku, Tokyo 100-0005 1-7 Description of the Address: applicant and inventor 11-6 State of nationality 11-6 State of nationality 11-1 This person is: applicant and inventor 11-1 This perso	0-3	Name of receiving Office and "PCT International Application"	
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Petition   The undersigned requests that the present international application be processed according to the Patent Cooperation Treaty	- '	•	DOM TROY Manager 2 00
The undersigned requests that the present international application be processed according to the Patent Cooperation Treaty  O-6 Receiving Office (specified by the applicant)  O-7 Applicant's or agent's file reference  I Title of invention  METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER, METHOD FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER, AND SYSTEM FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER, AND SYSTEM FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER  II Applicant  II-1 This person is:  II-2 Applicant for  II-8 State of nationality  JP  JP  JP  JP  JP  JP  JP  JP  JP  J	0-4-1	Prepared using	
present international application be processed according to the Patent Cooperation Treaty  0-6 Receiving Office (specified by the applicant)  0-7 Applicant's or agent's file reference  1 Title of invention  METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER, METHOD FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER, AND SYSTEM FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER  11 Applicant  11-1 This person is: 12 Applicant for 13 Address:  Address:  Address:  Address:  Address:  Address:  14-2, Marunouchi 1-chome Chiyoda-ku, Tokyo 100-0005 Japan JP JP JP State of residence  18-8 Telephone No. 19-9 Facsimile No. 19-9 Facsimile No. 19-1 Applicant and/or inventor 18-1-1 This person is: 18-1-1 Applicant and/or inventor 18-1-1 This person is: 18-1-1 Applicant and/or inventor 18-1-1 This person is: 18-1-1 Applicant for 18-1-1 Name (LAST, First) 18-1-1 This person is: 18-1-1 Applicant for 18-1-1 This person is: 18-1-1 Applicant and/or inventor 18-1-1 This person is: 18-1-1 Applicant for 18-1-1 This person is: 18-1-1 Applicant for 18-1-1 This person is: 18-1-1 Applicant and/or inventor 18-1-1 This person is: 18-1 Applicant and/or inventor 18-1 This person is: 18-2 This person is: 18-3 This person is: 18-4 This person is: 18-5 This person is: 18-6 This person is: 18-7 This person is: 18-8 This person is: 18-9 This person is: 18-1 This person is: 18-1 This person is: 18-2 This person is: 18-3 This person is: 18-4 This person is: 18-5 This person is: 18-6 This person is: 18-7 This person is: 18-8 This person is: 18-9 This person is: 18-9 This person is: 18-1 This person is: 18-1 This person is: 18-2 This person is: 18-3 This person is: 18-4 This person is: 18-5 This person is: 18-	0-5	Petition	
applicant) 0-7 Applicant's or agent's file reference 1 Title of invention  METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER, METHOD FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER, AND SYSTEM FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER  II Applicant This person is: applicant only all designated States except US Shin-Etsu Handotai Co., Ltd. 4-2, Marunouchi 1-chome Chiyoda-ku, Tokyo 100-0005 Japan II-6 State of nationality II-7 State of residence III-1-7 State of residence III-1-8 Applicant for III-1-1 Applicant for III-1-1 Applicant for III-1-2 Applicant for III-1-3 Address:  D1 O0291WO  METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER, METHOD FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER  applicant only applicant only applicant only applicant in Chome Chiyoda-ku, Tokyo 100-0005 Japan III-1-6 State of nationality  III-1-6 State of nationality  III-1-6 State of nationality  III-1-7 Applicant In Chome Chiyoda-ku, Tokyo 100-0005 Japan JP		present international application be processed according to the Patent	
Title of invention  METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER, METHOD FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER, AND SYSTEM FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER  II Applicant III-1 This person is: III-1 Applicant for III-1 Applicant and/or inventor III-1 Applicant and/or inventor III-1 Applicant for III	0-6		Japan Patent Office (RO/JP)
WAFER, METHOD FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER, AND SYSTEM FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER  II. Applicant III. This person is: III. Applicant for III. Applicant for III. Address:  III. Address:  III. Address:  III. State of nationality III. State of residence III. This person is: III. Applicant and/or inventor IIII. This person is: III. Applicant and/or inventor IIII. Applicant for III. Applica	0-7	Applicant's or agent's file reference	01 00291WO
MANUFACTURE OF SEMICONDUCTOR WAFER, AND SYSTEM FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER    Applicant	Ī	Title of invention	
SYSTEM FOR RECEIVING ORDER FOR MANUFACTURE OF SEMICONDUCTOR WAFER    Applicant			
MANUFACTURE OF SEMICONDUCTOR WAFER   II			
Applicant   This person is:   applicant only   all designated States except US			
II-1   This person is:   applicant only   all designated States except US     II-2   Applicant for   all designated States except US     II-4   Name   Shin-Etsu Handotai Co., Ltd.     II-5   Address:   4-2, Marunouchi 1-chome   Chiyoda-ku, Tokyo 100-0005     Japan   JP     II-7   State of residence   JP     II-8   Telephone No.   03-3214-1931     II-9   Facsimile No.   03-3215-9040     III-1   Applicant and/or inventor     III-1-1   This person is:   applicant and inventor     III-1-2   Applicant for   US only     III-1-4   Address:   C/o Head Office, Shin-Etsu Handotai Co., Ltd.     III-1-6   State of nationality   JP     III-1-6   State of nationality   JP     III-1-6   State of nationality   JP     III-1-7   Applicant only   Address:   C/o Head Office, Shin-Etsu Handotai Co., Ltd.     III-1-6   State of nationality   JP     III-1-7   JP   JP   JP   JP   JP   JP   JP   J		Audiood	MANUFACTURE OF SEMICONDUCTOR WAFER
II-2   Applicant for   all designated States except US     II-4   Name   Shin-Etsu Handotai Co., Ltd.     II-5   Address:		1 ''	
Name   Shin-Etsu Handotai Co., Ltd.		· ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	
Address:   4-2, Marunouchi 1-chome   Chiyoda-ku, Tokyo 100-0005   Japan   JP   II-6   State of nationality   JP   II-7   State of residence   JP   II-8   Telephone No.   03-3214-1931   03-3215-9040   III-1   Applicant and/or inventor   III-1-1   This person is:   applicant and inventor   III-1-2   Applicant for   US only   III-1-4   Name (LAST, First)   ITO, Tatsuo   C/o Head Office, Shin-Etsu Handotai Co.,   Ltd.   4-2, Marunouchi 1-chome   Chiyoda-ku, Tokyo 100-0005   Japan   JP   III-1-6   State of nationality   JP   JP   JP   JP   JP   JP   JP   J		, ,	
Chiyoda-ku, Tokyo 100-0005 Japan  JP State of residence JP Telephone No. 03-3214-1931 State of residence This person is: Chiyoda-ku, Tokyo 100-0005  Japan  JP  JP  JP  JP  JP  JP  JP  JP  JP  J			·
Japan   JP   State of nationality   JP   State of residence   JP   Telephone No.   03-3214-1931   11-9   Facsimile No.   03-3215-9040	11-5	Address.	·
II-6   State of nationality   JP   JP   II-7   State of residence   JP   II-8   Telephone No.   03-3214-1931   03-3215-9040     III-1   Applicant and/or inventor   III-1-1   This person is:   applicant and inventor   III-1-2   Applicant for   US only   III-1-4   Name (LAST, First)   ITO, Tatsuo   C/O Head Office, Shin-Etsu Handotai Co.,   Ltd.   4-2, Marunouchi 1-chome   Chiyoda-ku, Tokyo 100-0005   Japan   JP   III-1-6   State of nationality   JP   ITO   III-1-6   State of nationality   JP   ITO			
II-7   State of residence   JP   03-3214-1931   II-9   Facsimile No.   03-3215-9040   III-1   Applicant and/or inventor   III-1-1   This person is:   applicant and inventor   III-1-2   Applicant for   US only   III-1-4   Name (LAST, First)   ITO, Tatsuo   c/o Head Office, Shin-Etsu Handotai Co., Ltd.   4-2, Marunouchi 1-chome   Chiyoda-ku, Tokyo 100-0005   Japan   JP   III-1-6   State of nationality   JP   III-1-6   State of nationality   JP   III-1-1   III-1-	II-6	State of nationality	
II-8   Telephone No.   03-3214-1931   11-9   Facsimile No.   03-3215-9040   111-1   Applicant and/or inventor   III-1-1   This person is:   applicant and inventor   US only   III-1-2   Applicant for   US only   ITO, Tatsuo   C/o Head Office, Shin-Etsu Handotai Co.,   Ltd.   4-2, Marunouchi 1-chome   Chiyoda-ku, Tokyo 100-0005   Japan   JP			1
III-9   Facsimile No.   03-3215-9040     III-1   Applicant and/or inventor     III-1-1			
III-1   Applicant and/or inventor   III-1-1   This person is:   applicant and inventor   US only   III-1-2   Applicant for   US only   ITO, Tatsuo   III-1-5   Address:   c/o Head Office, Shin-Etsu Handotai Co.,   Ltd.   4-2, Marunouchi 1-chome   Chiyoda-ku, Tokyo 100-0005   Japan   JP		<u> </u>	
III-1-1 This person is:  III-1-2 Applicant for  III-1-4 Name (LAST, First)  III-1-5 Address:  Address:  C/o Head Office, Shin-Etsu Handotai Co., Ltd.  4-2, Marunouchi 1-chome Chiyoda-ku, Tokyo 100-0005 Japan  JP	III-1	Applicant and/or inventor	
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C/o Head Office, Shin-Etsu Handotai Co., Ltd. 4-2, Marunouchi 1-chome Chiyoda-ku, Tokyo 100-0005 Japan JP			
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Chiyoda-ku, Tokyo 100-0005  Japan  JP			
Chiyoda-ku, Tokyo 100-0005  Japan  JP			4-2, Marunouchi 1-chome
III-1-6 State of nationality Jp			
			Japan
III-1-7   State of residence   JP	III-1-6	State of nationality	JP
and the same of th	111-1-7	State of residence	JP



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III-2	Applicant and/or inventor	
III-2-1	This person is:	applicant and inventor
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III-2-4	Name (LAST, First)	NETSU, Shigeyoshi
III-2-5	Address:	c/o Shirakawa R&D Center, Shin-Etsu
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111-3	Applicant and/or inventor	
III-3-1	This person is:	applicant and inventor
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III-3 <b>-</b> 4	Name (LAST, First)	ICHIKAWA, Masashi
111-3-5	Address:	c/o Shirakawa R&D Center, Shin-Etsu
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		Japan
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III-3-7	State of residence	JP
111-4	Applicant and/or inventor	
III- <b>4</b> -1	This person is:	applicant and inventor
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111-4-5	Address:	c/o Shirakawa R&D Center, Shin-Etsu
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		150, Aza Ohira, Oaza Odakura,
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	}	Nishishirakawa-gun, Fukushima 961-8061
		Japan
11-4-6	State of nationality	JP
III-4-7 —	State of residence	JP

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IV-1	Agent or common representative; or	
	address for correspondence The person identified below is	agent
	hereby/has been appointed to act on behalf of the applicant(s) before the	agent
	competent International Authorities as:	
IV-1-1	Name (LAST, First)	YOSHIMIYA, Mikio
IV-1-2	Address:	Uenosansei Bldg. 4F
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	}	Taito-ku, Tokyo 111-0041
		Japan
IV-1-3	Telephone No.	03-3844-4501
IV-1-4	Facsimile No.	03-3844-4505
IV-1-5	e-mail	jdw07652@nifty.ne.jp
٧	Designation of States	
V-1	Regional Patent	EP: AT BE BG CH&LI CY CZ DE DK EE ES FI
	(other kinds of protection or treatment, if any, are specified between	FR GB GR HU IE IT LU MC NL PT SE SI SK
	parentheses after the designation(s)	TR and any other State which is a
	concerned)	Contracting State of the European Patent
		Convention and of the PCT
V-2	National Patent	KR US
	(other kinds of protection or treatment, if any, are specified between	·
	parentheses after the designation(s)	·
V-5	concerned) Precautionary Designation Statement	
	In addition to the designations made	
	under items V-1, V-2 and V-3, the	
	applicant also makes under Rule 4.9(b) all designations which would be	
	permitted under the PCT except any	
	designation(s) of the State(s) indicated	
	under item V-6 below. The applicant declares that those additional	
	designations are subject to confirmation	
	and that any designation which is not confirmed before the expiration of 15	
	months from the priority date is to be	
	regarded as withdrawn by the applicant at the expiration of that time limit.	
V-6	Exclusion(s) from precautionary	NONE
VI-1	designations Priority claim of earlier national	
	application	
VI-1-1	Filing date	29 January 2002 (29.01.2002)
VI-1-2	Number	2002-19334
VI-1-3	Country	JP
VI-2	Priority document request	
	The receiving Office is requested to prepare and transmit to the	VI-1
	International Bureau a certified copy of	
	the earlier application(s) identified above as item(s):	
VII-1	International Searching Authority	Japan Patent Office (JPO) (ISA/JP)
VII-1		Japan Patent Office (JPO) (ISA/JP)

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VIII	Declarations	Number of declarations	<u> </u>
VIII-1	Declaration as to the identity of the inventor	-	
VIII-2	Declaration as to the applicant's entitlement, as at the international filing date, to apply for and be granted a patent		
VIII-3	Declaration as to the applicant's entitlement, as at the international filing date, to claim the priority of the earlier application	_	
VIII-4	Declaration of inventorship (only for the purposes of the designation of the United States of America)	_	
VIII-5	Declaration as to non-prejudicial disclosures or exceptions to lack of novelty	-	
IX	Check list	number of sheets	electronic file(s) attached
IX-1	Request (including declaration sheets)	6 .	<b> -</b>
IX-2	Description	23	-
IX-3	Claims	4	-
IX-4	Abstract	1	-
IX-5	Drawings	6	-
IX-7	TOTAL	40	
	Accompanying items	paper document(s) attached	electronic file(s) attached
IX-8	Fee calculation sheet	<b>✓</b>	-
IX-17	PCT-EASY diskette	_	Diskette
IX-19	Figure of the drawings which should accompany the abstract	1	
IX-20	Language of filing of the international application	Japanese	
X	Signature of applicant, agent or common representative		
X-1	Name (LAST, First)	1	
X-2	Capacity		

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10-1	Date of actual receipt of the purported international application	
10-2	Drawings:	
10-2-1	Received	
10-2-2	Not received	
10-3	Corrected date of actual receipt due to later but timely received papers or drawings completing the purported international application	-
10-4	Date of timely receipt of the required corrections under PCT Article 11(2)	
10-5	International Searching Authority	ISA/JP
10-6	Transmittal of search copy delayed until search fee is paid	

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**PCT REQUEST** 

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	the International Bureau	
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